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DESCRIPTION

The LX5537 is a power amplifier optimized for 802.16e(WiMAX/WiBro) and 802.11b/g/n applications in the 2.3-2.7 GHz frequency range. The PA is implemented as a three-stage monolithic microwave integrated circuit (MMIC) with active bias, on-chip input matching and output pre-matching.

The device is manufactured with an InGaP/GaAs Heterojunction Bipolar Transistor (HBT) IC process (MOCVD). It operates with a single positive voltage supply of 3-4.2V, and provides power gain of 31dB and output powers of +23.5dBm at 3.6V and +25 dBm at 4.2V for 2.5% EVM in the 2.5-2.7GHz.

LX5537 also features an on-chip power detector at the output port of the PA to help reduce BOM cost and PCB space for implementation of power control in a typical wireless system. The 26dB attenuation function can optionally be used to reach low gain mode.

The LX5537 is available in a 16-pin 3mm x 3mm quad flat no lead package (QFN 3x3-16L). The compact footprint, low profile, and excellent thermal capability make the LX5537 an ideal solution for WiMAX/WiBro as well as 802.11b/g/n applications.

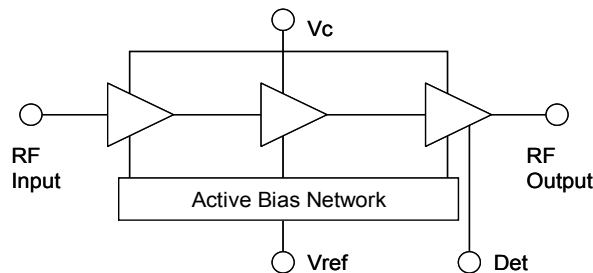
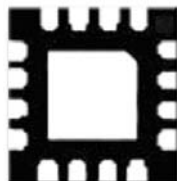
IMPORTANT: For the most current data, consult MICROSEMI's website: <http://www.microsemi.com>

KEY FEATURES

- Advanced InGaP HBT
- 2.3-2.7GHz Operation
- Single-Polarity 3-4.2V Supply
- Power Gain ~ 31 dB or higher
- 23.5 dBm @2.5% EVM /3.6V
- 25 dBm @2.5% EVM /4.2V
- 24.5 dBm @4% EVM /3.6V
- 26 dBm @4% EVM /4.2V
- 22% Efficiency @24.5dBm/3.6V
- Optional 26dB Attenuation
- Complete On-Chip Input Match
- Simple Output Match for Optimal EVM
- Temperature-Compensated On-Chip Output Power Detector with Wide Dynamic Range
- Small Footprint: 3x3mm²
- Low Profile: 0.9mm

APPLICATIONS

- 802.16e WiMAX
- 802.16e WiBro
- 802.11b/g/n

BLOCK DIAGRAM

3X3MM QFN PACKAGE

PACKAGE ORDER INFO
LQ

 Plastic QFN 3x3
 16 pin

RoHS Compliant / Pb-free

LX5537LQ

Note: Available in Tape & Reel. Append the letters "TR" to the part number. (i.e. LX5537LQ-TR)



Microsemi[®]

INFORMATION

Thank you for your interest in Microsemi[®] Analog Mixed Signal products.

The full data sheet for this device contains proprietary information.

To obtain a copy, please contact your local Microsemi sales representative. The name of your local representative can be obtained at the following link

<http://www.microsemi.com/contact/contactfind.asp>

or

Contact us directly by sending an email to:

IPGdatasheets@microsemi.com

Be sure to specify the data sheet you are requesting and include your company name and contact information and or vcard.

We look forward to hearing from you.